



## Material Content Data Sheet



<b>Sales Product Name</b>		TDA4863G		<b>Issued</b>		20. May 2015			
<b>MA#</b>		MA001367866							
<b>Package</b>		PG-DSO-8-41		<b>Weight*</b>		81.24 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.391	4.17	4.17	41738	41738	
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104		
	non noble metal	zinc	7440-66-6	0.034	0.04		414		
	non noble metal	iron	7439-89-6	0.673	0.83		8285		
wire	non noble metal	copper	7440-50-8	27.330	33.64	34.52	336408	345211	
	noble metal	gold	7440-57-5	0.091	0.11	0.11	1126	1126	
	encapsulation	organic material	carbon black	1333-86-4	0.142	0.17		1742	
plastics	plastics	epoxy resin	-	4.575	5.63		56319		
	inorganic material	silicondioxide	60676-86-0	42.453	52.27	58.07	522547	580608	
leadfinish	non noble metal	tin	7440-31-5	0.824	1.01	1.01	10143	10143	
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1102	1102	
glue	plastics	acrylic resin	-	0.326	0.40		4014		
	noble metal	silver	7440-22-4	1.305	1.61	2.01	16058	20072	
*deviation	< 10%				Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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